APPLICA	BLE STAN	DARD										
OPERATING TEMPERATUR		RE RANGE	-55 °C TO 85 °C (1) STORAGE TEMPERA				60 °) °C (2)				
RATING	VOLTAGE		100 V AC			STORAGE HUMIDITY RANGE			40 % TO	% (2)	ı	
	CURRENT					PERATING HUMIDITY ANGE			RELATIVE HUMI	85% n	nax	
			3 A (MF CONTACT)						(NOT DEWED)			
			SPEC	IFIC	AOITA	IS						
ΙΤ	EM		TEST METHOD				RE	QUI	IREMENTS		QT	АТ
CONSTRI	JCTION											
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.				ACCORDING TO DRAWING.					×	×
MARKING		CONFIRMED VISUALLY.				1					×	×
ELECTRIC CHARAC		TERISTICS										
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)					SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX.					<u> </u>
INSULATION RESISTANCE		250 V DC.					1000 M			=	×	_
VOLTAGE PROOF		300 V AC FOR 1 min. NO FLASHOVER OR BREAKDOW								×	 	
MECHANI	CAL CHAR	ACTER	ISTICS									
INSERTION AND		MEASURED BY APPLICABLE CONNECTOR.				INSERTION FORCE: 40 N MAX.						_
WITHDRAWAL FORCES						WITHDRAWAL FORCE: 4 N MIN.						
MECHANICA		500 TIMES INSERTIONS AND EXTRACTIONS.			NS.	① CONTACT RESISTANCE:					×	_
OPERATION						SIGNAL CONTACT : 100 m Ω MAX.						l
						MF CONTACT : 40 mΩ MAX. Δ1						
						1		E, CR	RACK AND LOOSENE	ESS		
VIBRATION		EDECLIENCY 40 TO 55 TO 4011- ADDDOV 5 to 10					PARTS.	NO 41	DIOCONITINUUTY OF			
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES				① NO ELECTRICAL DISCONTINUITY OF 1 μs.						_
		1	DIRECTIONS.	TOLLO				F CR	RACK AND LOOSENE	- -SS		
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms				OF PARTS.					×	_
			TIMES FOR 3 DIRECT									
ENVIRON	MENTAL C	HARAC	TERISTICS									
DAMP HEAT		EXPOSE	DAT 40±2°C, 90 ~ 95	5 %, 96	6 h.	① CO	NTACT F	RESIS	STANCE:		×	_
(STEADY STATE)						1			CT : 100 m Ω MAX.	Δ		
RAPID CHANGE OF		TEMPERATURE -55 → +85 °C				MF CONTACT : $40 \text{ m}\Omega$ MAX. $\Delta \Omega$					×	_
TEMPERATU	JRE	TIME		in.		2 INS	ULATION	N RES	SISTANCE			
		UNDER				@ NO			M Ω M 0001:			
		RELOCA	TION TIME TO CHAMBER:WITH	IIN 2~3	MIN)	I	PARTS.	E, CR	RACK AND LOOSENE	:55		
SULFUR DIC	XIDE	EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h.			NO HEAVY CORROSION.					×	\vdash	
		(TEST ST	ANDARD: JIS C 60068)									
RESISTANCE TO		1)REFLOW SOLDERING :			NO DEFORMATION OF CASE OF					×	_	
SOLDERING HEAT SOLDERABILITY		PEAK TMP: 260°CMAX			EXCESSIVE LOOSENESS OF THE							
		REFLOW TMP: 220°CMIN FOR 60sec				TERMINAL. A NEW UNIFORM COATING OF SOLDER						
		2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.										-
		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.			- C	SHALL COVER A MINIMUM OF 95 % OF THE					×	
		240±0 0 1 GK IMMERCION BOTATION, 0 366.				SURFACE BEING IMMERSED.						
<u> </u>									2			<u> </u>
COUN	<u>T D</u>	ESCRIPTI	ON OF REVISIONS	+		GNED			CHECKED		DA	TE
6					TH. S	SANO		KI. HIROKAWA		09.09	9. 15	
		PERATURE RISE CAUSED BY CURRENT-CARRYING. EANS A LONG-TERM STORAGE STATE USED PRODUCT BEFORE ASSEMBLY TO PCB. USERNT APPLIES TO PER CONTACT.				APPROVED CHECKED DESIGNED		HS. OKAWA			4. 28	
								HS. OZAWA			4. 28	
								KI.HIROKAWA		09. 04. 2		
Holooc -41-	onvice cara					DRAWN			KI HIBUKYMY	I. HIROKAWA 09. (
Unless otherwise specified,												7. 20
		t AT:Assurance Test X:Applicable Test				DRAWING NO.			ELC4-159561-00 FX18-60P-0. 8SV			
HS.			CATION SHEET		PART NO.		0.1	Α.				
l	HIR	OSF F	LECTRIC CO., LTD.		CODE NO.		CL579-0017-2-00			_/	11	1/1